



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D
* : Required Field			

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2015-10-26
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMS MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement

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Legal Statement


Supplier Acceptance *	true	Legal Declaration *	Standard
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Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
TS924AIDT	LDK7*0924AR6	A	BO2A	2015-10-26
Amount	UoM	Unit type	ST ECOPACK Grade	
130.00	mg	Each	ECOPACK® 3	
	Comment	ECOPACK® 3 is STMicroelectronics trade name for ROHS compliant device without use of any ROHS exemption and without Halogen nor Antimony		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
NAC	Tin (Sn), matte, annealed	Copper Alloy		



Package Designator	Size	Nbr of instances	Shape	
DSO	8.6x3.9x1.52	14	gull wing	
Comment	Package: K7 SO 14 .15 TO JEDEC MS-012; MDF valid also for TS9224IDT-TS924AIDT/DEL-TS924ID-TS924IDT-TS954IDT			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
Exemption Id.	Description

QueryList : REACH-15th June 2015				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	LDK7*0924AR6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	4.282	mg	supplier	die	Silicon (Si)	7440-21-3		4.251	mg	992760	32700
				supplier	metallization	Aluminium (Al)	7429-90-5		0.011	mg	2569	85
				supplier	Passivation	Silicon Nitride	12033-89-5		0.008	mg	1868	62
				supplier	Passivation	Silicon Oxide	7631-86-9		0.006	mg	1401	46
				supplier	glass coating	Glass: Silicon Dioxide	7631-86-9		0.006	mg	1401	46
Leadframe	Copper & its alloys	37.969	mg	supplier	alloy	Copper (Cu)	7440-50-8		34.861	mg	918144	268162
				supplier	alloy	Iron (Fe)	7439-89-6		0.820	mg	21597	6308
				supplier	alloy	Iron Phosphide (FeP)	26508-33-8		0.049	mg	1291	377
				supplier	alloy	Zinc (Zn)	7440-66-6		0.043	mg	1133	331
				supplier	metallization	Nickel (Ni)	7440-02-0		0.460	mg	12115	3538
				supplier	metallization	Palladium (Pd)	7440-05-3		0.029	mg	764	223
				supplier	metallization	Gold (Au)	7440-57-5		0.012	mg	316	92
				supplier	metallization	Silver (Ag)	7440-22-4		1.695	mg	44642	13038
				supplier	glue	Silver (Ag)	7440-22-4		1.036	mg	907975	7969
Die attach	Other inorganic materials	1.141	mg	supplier	glue	acrylate	Proprietary		0.057	mg	4956	438
				supplier	glue	Methacrylate	Proprietary		0.046	mg	40316	354
				supplier	glue	acrylate	Proprietary		0.001	mg	876	8
				SVHC	glue	NMP	872-50-4		0.001	mg	876	8
				supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	977
Bonding wires	Other inorganic materials	0.127	mg	supplier	wire	Copper (Cu)	7440-50-8		0.127	mg	1000000	977
				supplier	mold compound	Silica, vitreous	60676-86-0		75.056	mg	877007	577354
				supplier	mold compound	Epoxy resin	85954-11-6		3.423	mg	39997	26331
				supplier	mold compound	Epoxy	29690-82-2		3.423	mg	39997	26331
				supplier	mold compound	phenol resin	Proprietary		2.567	mg	29995	19746
Encapsulation	Other Organic Materials	85.582	mg	supplier	mold compound	additive	Proprietary		0.856	mg	10002	6585
				supplier	mold compound	carbon black	1333-86-4		0.257	mg	3003	1977
				supplier	solder alloy	Tin (Sn)	7440-31-5		0.900	mg	1000000	6923
connections coating	Solder	0.900	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		0.900	mg	1000000	6923